

ABSTRACT

A chip structure and a bonding pad are provided. The chip structure comprises a chip and at least a bonding pad. The chip has an active surface. The bonding pad is disposed on the active surface of the chip. The bonding pad comprises a polygonal body and a plurality of first protruding portions. The polygonal body has a first planar surface and a corresponding second planar surface. The second planar surface of the polygonal body is in contact with the chip. The first protruding portions are disposed on the first planar surface at the corner regions of the polygonal body. By modifying the geometric shape of the bonding pad, the yield of bonding the chip structure and another device together through the bonding pad is increased.